

Gold Epoxy Adhesive

Technical Product Bulletin

PRODUCT DESCRIPTION:

AA-BOND G298 is a two component, gold-filled, electrically and thermally conductive epoxy designed for hybrid microelectronic high reliability applications.

AA-BOND G298 is non-oxidizing and prevents electromigration.

PRODUCT PROPERTIES:

Color	Part A (Resin): Brown Part B (Hardener): Clear to yellowish
Cure Type	Room Temperature or Heat cure
Benefits	<ul style="list-style-type: none"> • No electromigration • Antioxidation • Good thermal shock • Room temperature cure
Mix Ratio by weight	100:4 Resin to Hardener
Substrates	Metal, Glass, aluminum, steel, bronze, nickel, ceramic and Etc.
Operating Temperature	-40°C (-40°F) to +175°C (347°F)
Typical Applications	<ul style="list-style-type: none"> • Adhesive for die attach and SMDs onto the hybrid circuits. • Resisting oxidation and electro-migration in high-reliability micro-electronics.

UNCURED PROPERTIES:

Viscosity @ 25 °C cps	600,000±50,000
Specific Gravity gm/cc	Mixed: 5.15
Reactive solids contents, %	100
Pot Life to double the viscosity	45 minutes at 25°C (77°F)
Particle Size:	≤ 50 Microns

CURE SCHEDULE:

24 hours	At 25°C (77°F)
3 hours	At 65°C (149°F)
1 hour	At 100°C (212°F)

CURED PROPERTIES:

Hardness, Shore D	87
Water Absorption	0.18% after 24 hours
Volume Resistivity ohm. cm	≤ 0.0009
Lap Shear Strength alum to alum, PSI	1700

GENERAL INFORMATION:

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

HOW TO USE:

1. Carefully clean and dry all surfaces to be bonded.
2. Apply this completely mixed adhesive to the prepared surfaces, and gently press these surfaces together. Contact pressure is adequate for strong, reliable bonds; however, maintain contact until adhesive is completely cured.
3. Some separation of components is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use.
4. Some ingredients in this formulation provided may crystallize when subjected to low temperature storage. A gentle warming cycle of 52°C for 30 minutes prior to mixing components may be necessary. Crystallized epoxy components do not react as well as liquid components and should be re-dissolved prior to use for best results.
5. Allow the product to cure according to the cure schedule.

AVAILABILITY:

This epoxy can be supplied in many different packages.

Atom Adhesives

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